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74ABT240

Octal Buffer/Line Driver with 3-STATE Outputs

General Description

The ABT240 is an inverting octal buffer and line driver designed to be employed as a memory address driver, clock driver and bus oriented transmitter or receiver which provides improved PC board density.

Features

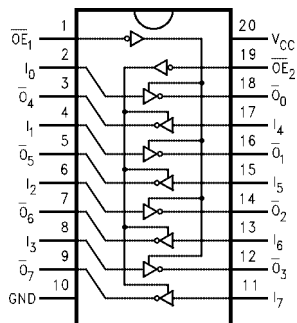
- Output sink capability of 64 mA, source capability of 32 mA
- Guaranteed latchup protection
- High impedance glitch free bus loading during entire power up and power down cycle
- Nondestructive hot insertion capability

Ordering Code:

Order Number	Package Number	Package Description
74ABT240CSC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74ABT240CSJ	M20D	Pb-Free 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74ABT240CMSA	MSA20	20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide
74ABT240CMTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code.
Pb-Free package per JEDEC J-STD-020B.

Connection Diagram



Pin Descriptions

Pin Names	Description
$\overline{OE}_1, \overline{OE}_2$	3-STATE Output Enable Inputs
I_0-I_7	Inputs
$\overline{O}_0-\overline{O}_7$	Outputs

Truth Tables

Inputs		Outputs (Pins 12, 14, 16, 18)
\overline{OE}_1	I_n	
L	L	H
L	H	L
H	X	Z

Inputs		Outputs (Pins 3, 5, 7, 9)
\overline{OE}_2	I_n	
L	L	H
L	H	L
H	X	Z

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = High Impedance

Absolute Maximum Ratings(Note 1)

Storage Temperature	–65°C to +150°C
Junction Temperature under Bias	–55°C to +150°C
V _{CC} Pin Potential to Ground Pin	–0.5V to +7.0V
Input Voltage (Note 2)	–0.5V to +7.0V
Input Current (Note 2)	–30 mA to +5.0 mA
Voltage Applied to Any Output in the Disabled or Power-Off State	–0.5V to 5.5V
in the HIGH State	–0.5V to V _{CC}
Current Applied to Output in LOW State (Max)	twice the rated I _{OL} (mA)
DC Latchup Source Current (Across Comm Operating Range)	–150 mA
Over Voltage Latchup (I/O)	10V

Recommended Operating Conditions

Free Air Ambient Temperature	–40°C to +85°C
Supply Voltage	+4.5V to +5.5V
Minimum Input Edge Rate ($\Delta V/\Delta t$)	
Data Input	50 mV/ns
Enable Input	20 mV/ns

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

DC Electrical Characteristics

Symbol	Parameter	Min	Typ	Max	Units	V _{CC}	Conditions
V _{IH}	Input HIGH Voltage	2.0			V		Recognized HIGH Signal
V _{IL}	Input LOW Voltage			0.8	V		Recognized LOW Signal
V _{CD}	Input Clamp Diode Voltage			–1.2	V	Min	I _{IN} = –18 mA
V _{OH}	Output HIGH Voltage	2.5			V	Min	I _{OH} = –3 mA
		2.0			V	Min	I _{OH} = –32 mA
V _{OL}	Output LOW Voltage			0.55	V	Min	I _{OL} = 64 mA
I _{IH}	Input HIGH Current			1	μA	Max	V _{IN} = 2.7V (Note 3)
				1	μA	Max	V _{IN} = V _{CC}
I _{BVI}	Input HIGH Current Breakdown Test			7	μA	Max	V _{IN} = 7.0V
I _{IL}	Input LOW Current			–1	μA	Max	V _{IN} = 0.5V (Note 3)
				–1	μA	Max	V _{IN} = 0.0V
V _{ID}	Input Leakage Test	4.75			V	0.0	I _{ID} = 1.9 μA All Other Pins Grounded
I _{OZH}	Output Leakage Current			10	μA	0 – 5.5V	V _{OUT} = 2.7V; \overline{OE}_n = 2.0V
I _{OZL}	Output Leakage Current			–10	μA	0 – 5.5V	V _{OUT} = 0.5V; \overline{OE}_n = 2.0V
I _{OS}	Output Short-Circuit Current	–100		–275	mA	Max	V _{OUT} = 0.0V
I _{CEX}	Output HIGH Leakage Current			50	μA	Max	V _{OUT} = V _{CC}
I _{ZZ}	Bus Drainage Test			100	μA	0.0	V _{OUT} = 5.5V; All Others GND
I _{CCH}	Power Supply Current			50	μA	Max	All Outputs HIGH
I _{CCL}	Power Supply Current			30	mA	Max	All Outputs LOW
I _{CCZ}	Power Supply Current			50	μA	Max	\overline{OE}_n = V _{CC} ; All Others at V _{CC} or Ground
I _{CCT}	Additional I _{CC} /Input Outputs Enabled			1.5	mA	Max	V _I = V _{CC} – 2.1V
				1.5	mA		Enable Input V _I = V _{CC} – 2.1V
				50	μA		Data Input V _I = V _{CC} – 2.1V All Others at V _{CC} or Ground
I _{CCD}	Dynamic I _{CC} No Load (Note 3)			0.1	mA/ MHz	Max	Outputs Open \overline{OE}_n = GND, (Note 4) One Bit Toggling, 50% Duty Cycle

Note 3: Guaranteed, but not tested.

Note 4: For 8 bits toggling, I_{CCD} < 0.8 mA/MHz.

AC Electrical Characteristics

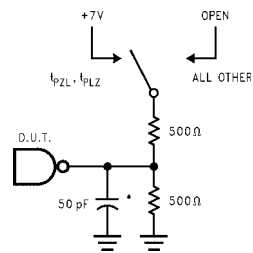
Symbol	Parameter	T _A = +25°C V _{CC} = +5V C _L = 50 pF			T _A = -55°C to +125°C V _{CC} = 4.5V–5.5V C _L = 50 pF		T _A = -40°C to +85°C V _{CC} = 4.5V–5.5V C _L = 50 pF		Units
		Min	Typ	Max	Min	Max	Min	Max	
t _{PLH}	Propagation Delay	1.0		4.8	0.8	5.5	1.0	4.8	ns
t _{PHL}	Data to Outputs	1.6		4.8	1.0	5.5	1.6	4.8	
t _{PZH}	Output Enable	1.1		6.2	0.8	7.5	1.1	6.2	ns
t _{PZL}	Time	1.1		6.2	0.8	7.7	1.1	6.2	
t _{PHZ}	Output Disable	1.8		6.4	1.0	7.5	1.8	6.4	ns
t _{PLZ}	Time	1.6		5.8	1.0	7.2	1.6	5.8	

Capacitance

Symbol	Parameter	Typ	Units	Conditions T _A = 25°C
C _{IN}	Input Capacitance	5.0	pF	V _{CC} = 0V
C _{OUT} (Note 5)	Output Capacitance	9.0	pF	V _{CC} = 5.0V

Note 5: C_{OUT} is measured at frequency f = 1 MHz, per MIL-STD-883, Method 3012.

AC Loading



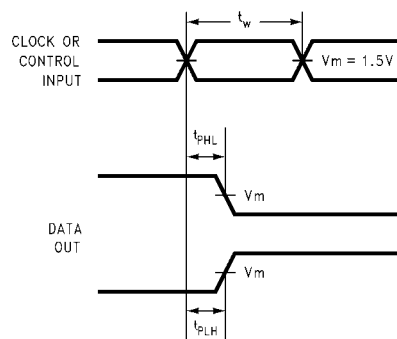
*Includes jig and probe capacitance

Standard AC Test Load

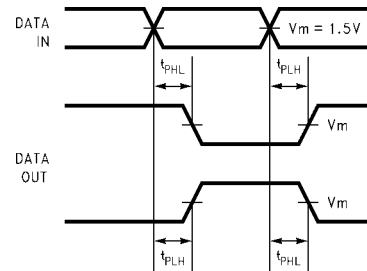
Amplitude	Rep. Rate	t_w	t_r	t_f
3.0V	1 MHz	500 ns	2.5 ns	2.5 ns

Test Input Signal Requirements

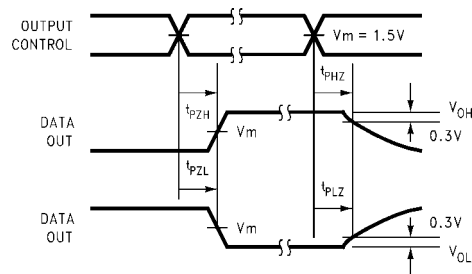
AC Waveforms



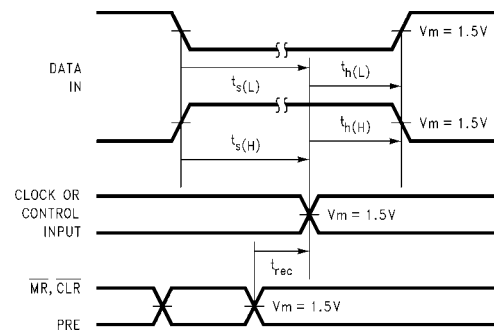
Propagation Delay,
Pulse Width Waveforms



Propagation Delay Waveforms for
Inverting and Non-Inverting Functions

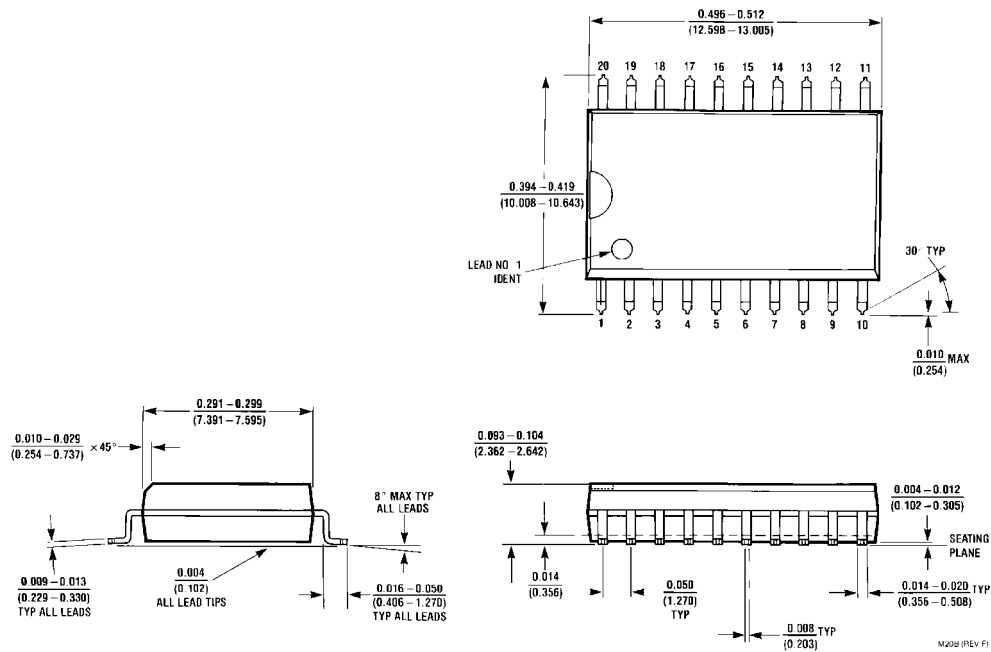


3-STATE Output HIGH
and LOW Enable and Disable Times



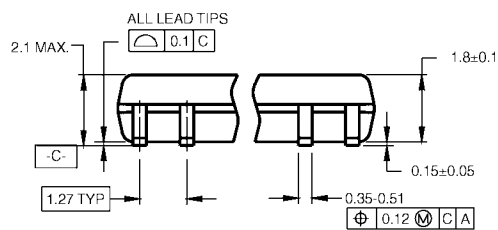
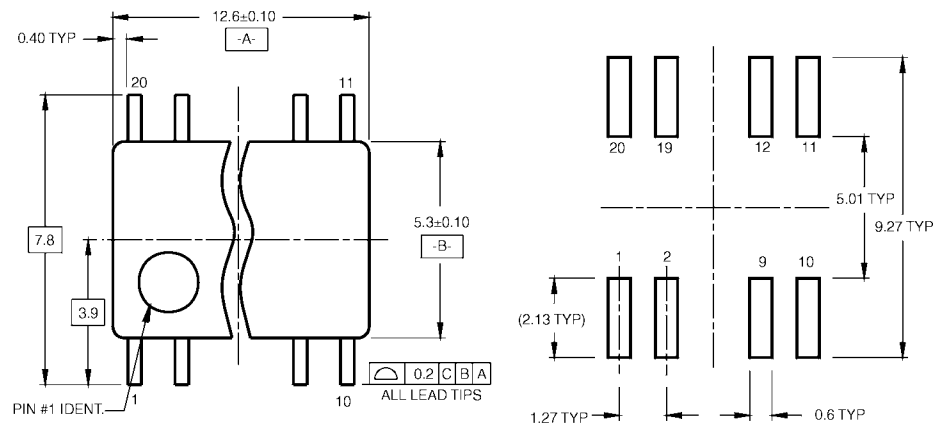
Setup Time, Hold Time
and Recovery Time Waveforms

Physical Dimensions inches (millimeters) unless otherwise noted



20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
Package Number M20B

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

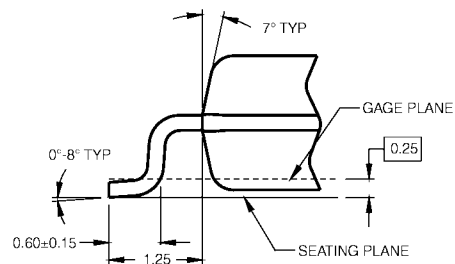


DIMENSIONS ARE IN MILLIMETERS

NOTES:

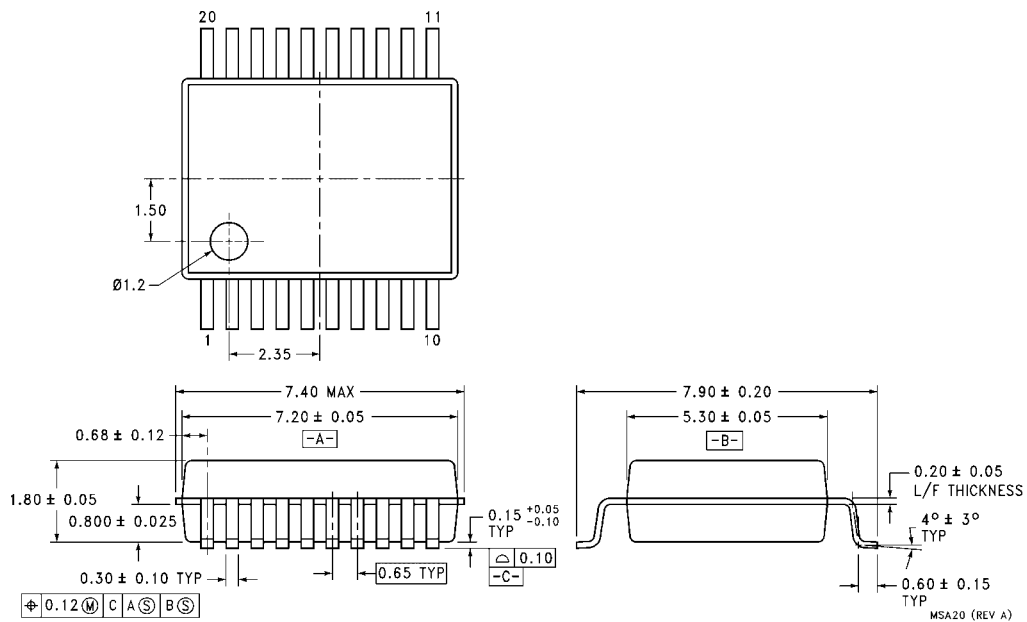
- CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
- DIMENSIONS ARE IN MILLIMETERS.
- DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M20DRevB1



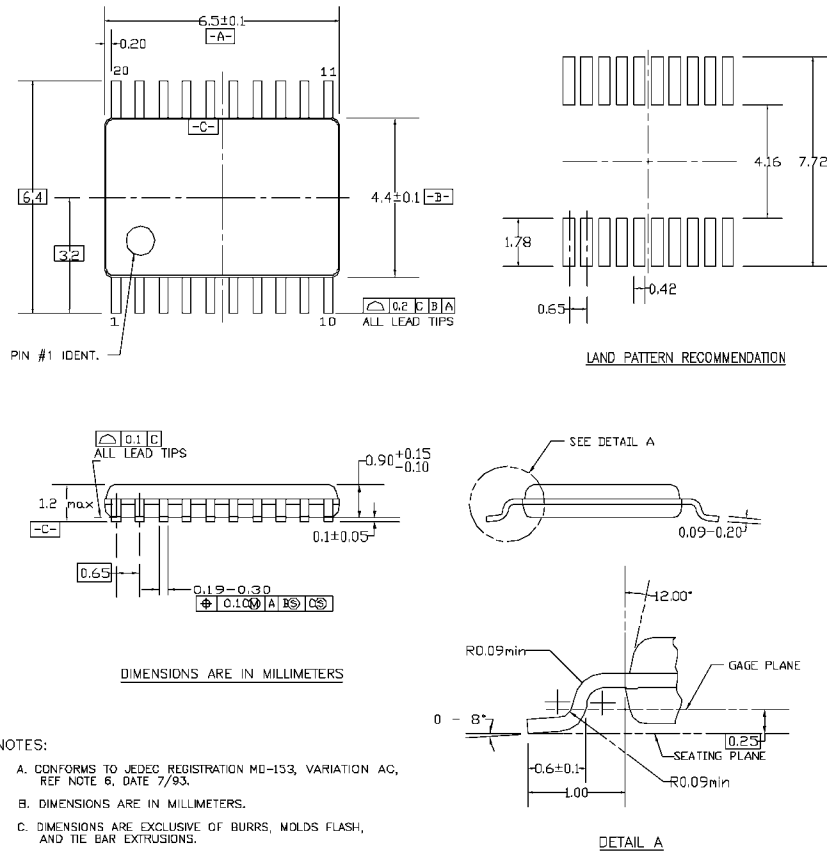
DETAIL A

**Pb-Free 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M20D**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)


20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide
Package Number MSA20

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



MTC20REV D1

20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC20

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